BGA Heat Sink - High Performance maxiFLOW/superGRIP



ATS Part#:

Description:

ATS-X50310G-C1-R0

31.00 x 31.00 x 12.50 mm BGA Heat Sink - High Performance maxiFLOW/superGRIP

Heat Sink Type: maxiFLOW Heat Sink Attachment: Equivalent Part Number: N/A

superGRIP

*Image above is for illustration purpose only.

Features & Benefits

- Designed for 31 x 31 mm components •
- Requires minimal space around the component's perimeter; ideal for densely populated PCBs •
- Allows the heat sink to be detached and reattached without damaging the component or the PCB, an important feature in the event a • PCB may need to be reworked
- Strong, uniform attachment force helps achieve maximum performance from phase-changing TIMs
- Eliminates the need to drill mounting holes in the PCB .

Thermal Performance

		@200 LFM 1.0 M/S			@700 LFM 3.5 M/S	@800 LFM 4.0 M/S		
THERMAL RESISTANCE	Unducted Flow	4.3 °C/W	3.5 °C/W	3 °C/W	2.7 °C/W	2.5 °C/W	2.3 °C/W	2.2 °C/W
	Ducted Flow	3.5	N/A	N/A	N/A	N/A	N/A	N/A

Product Detail

Schematic Image	Dimension A	Dimension B	Dimension C	Dimension D	ТІМ	Finish
	31.00 mm	31.00 mm	12.50 mm	54.9 mm	T766	BLUE-ANODIZED
The above is for illustration purpose only.	 Dimension Thermal papplication ATS resense performant ATS certification 	performance data are n. rves the right to upda nce. ies that this heat sin	omponent size. neight from the bottor e provided for referen ate or change its pro- k assembly is RoHS ustom options availat	nce only. Actual perfo ducts without notice -6 and REACH com	ormance to improv	may vary by

For more information, to find a distributor or to place an order, please contact us at 781-769-2800 (North America), sales@qats.com or www.qats.com.

